

# **4V Drive Pch MOSFET**

#### RRR015P03

#### Structure

Silicon P-channel MOSFET

#### Features

- 1) Low On-resistance.
- 2) High power package.
- 3) 4V drive.

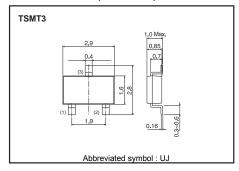
#### Application

Switching

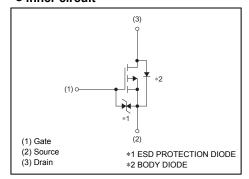
Packaging specifications

Type	Package	Taping
	Code	TL
	Basic ordering unit (pieces)	3000
RRR015P03		0

#### Dimensions (Unit : mm)



#### • Inner circuit



## ● Absolute maximum ratings (Ta = 25°C)

Parameter		Symbol Limits		Unit
Drain-source voltage		$V_{DSS}$	-30	V
Gate-source voltage		$V_{GSS}$	±20	V
Drain current	Continuous	$I_D$	±1.5	Α
	Pulsed	I <sub>DP</sub> *1	<u>±</u> 6	Α
Source current	Continuous	I <sub>S</sub>	-0.8	Α
(Body Diode)	Pulsed	I <sub>SP</sub> *1	-6	Α
Power dissipation		P <sub>D</sub> *2	1.0	W
Channel temperature		Tch 150		°C
Range of storage temperature		Tstg	-55 to +150	°C

<sup>\*1</sup> Pw≤10µs, Duty cycle≤1%

#### Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to Ambient	Rth (ch-a)*	125	°C / W

<sup>\*</sup>Mounted on a ceramic board.

<sup>\*2</sup> Mounted on a ceramic board.

## ● Electrical characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$	-	-	±10	μ <b>A</b>	$V_{GS}=\pm20V$ , $V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	-30	-	-	V	$I_D$ =-1mA, $V_{GS}$ =0V
Zero gate voltage drain current	I <sub>DSS</sub>	ı	1	-1	μA	$V_{DS}$ =-30V, $V_{GS}$ =0V
Gate threshold voltage	V <sub>GS (th)</sub>	-1.0	1	-2.5	V	$V_{DS}$ =-10V, $I_{D}$ =-1mA
Static drain-source on-state resistance	*	ı	115	160		I <sub>D</sub> =-1.5A, V <sub>GS</sub> =-10V
	R <sub>DS (on)</sub>	ı	170	240	mΩ	$I_D = -0.7A, V_{GS} = -4.5V$
		ı	190	270		I <sub>D</sub> =-0.7A, V <sub>GS</sub> =-4.0V
Forward transfer admittance	IY <sub>fs</sub> ľ	1.2	1	-	S	V <sub>DS</sub> =-10V, I <sub>D</sub> =-1.5A
Input capacitance	C <sub>iss</sub>	ı	230	-	pF	V <sub>DS</sub> =-10V
Output capacitance	C <sub>oss</sub>	1	40	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	1	33	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	1	12	-	ns	I <sub>D</sub> =-0.7A, V <sub>DD</sub> ≒-15V
Rise time	t <sub>r</sub> *	ı	8	-	ns	V <sub>GS</sub> =-10V
Turn-off delay time	t <sub>d(off)</sub> *	ı	40	-	ns	R <sub>L</sub> ≒21.4Ω
Fall time	t <sub>f</sub> *	ı	13	-	ns	$R_G$ =10 $\Omega$
Total gate charge	Q <sub>g</sub> *	-	3.2	-	nC	I <sub>D</sub> =-1.5A, V <sub>DD</sub> ≒-15V
Gate-source charge	Q <sub>gs</sub> *	-	1.2	-	nC	V <sub>GS</sub> =–5V R <sub>L</sub> ≒10Ω
Gate-drain charge	Q <sub>gd</sub> *	-	0.7	-	nC	$R_G$ =10 $\Omega$

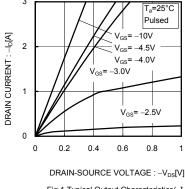
<sup>\*</sup>Pulsed

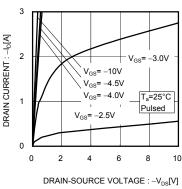
## ●Body diode characteristics (Source-Drain) (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward Voltage	$V_{SD}^{*}$	-	-	-1.2	V	I <sub>s</sub> =-1.5A, V <sub>GS</sub> =0V

<sup>\*</sup>Pulsed

#### Electrical characteristic curves





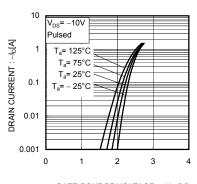
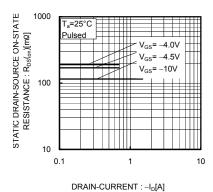


Fig.1 Typical Output Characteristics( I )

Fig.2 Typical Output Characteristics( II)

GATE-SOURCE VOLTAGE :  $-V_{GS}[V]$ Fig.3 Typical Transfer Characteristics



1000 STATIC DRAIN-SOURCE ON-STATE /<sub>GS</sub>= -10V T<sub>a</sub>= 125°C T<sub>a</sub>= 75°C Pulsed  $R_{DS}(m)[m\Omega]$ T<sub>a</sub>= 25°C – 25°C RESISTANCE: 100 10 0.1 10 DRAIN-CURRENT : -I<sub>D</sub>[A]

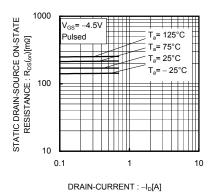
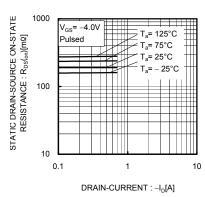
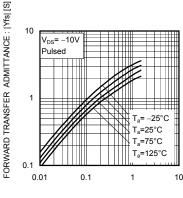


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

Fig.5 Static Drain-Source On-State Resistance vs. Drain Current( II )

Fig.6 Static Drain-Source On-State Resistance vs. Drain Current( III )





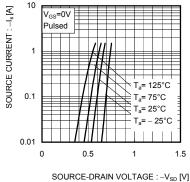
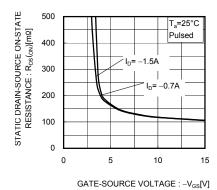
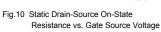


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current( IV)

DRAIN-CURRENT : -I<sub>D</sub>[A] Fig.8 Forward Transfer Admittance vs. Drain Current

Fig.9 Reverse Drain Current vs. Sourse-Drain Voltage





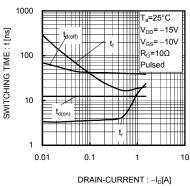


Fig.11 Switching Characteristics

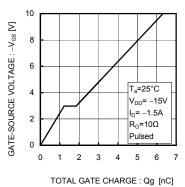
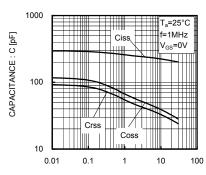


Fig.12 Dynamic Input Characteristics



DRAIN-SOURCE VOLTAGE : -V<sub>DS</sub>[V]
Fig.13 Typical Capacitance
vs. Drain-Source Voltage

#### Measurement circuits

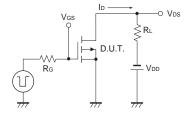


Fig.1-1 Switching time measurement circuit

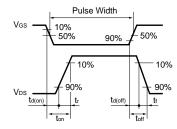


Fig.1-2 Switching Waveforms

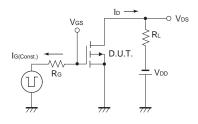


Fig.2-1 Gate charge measurement circuit

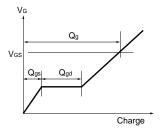


Fig.2-2 Gate Charge Waveform

#### Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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